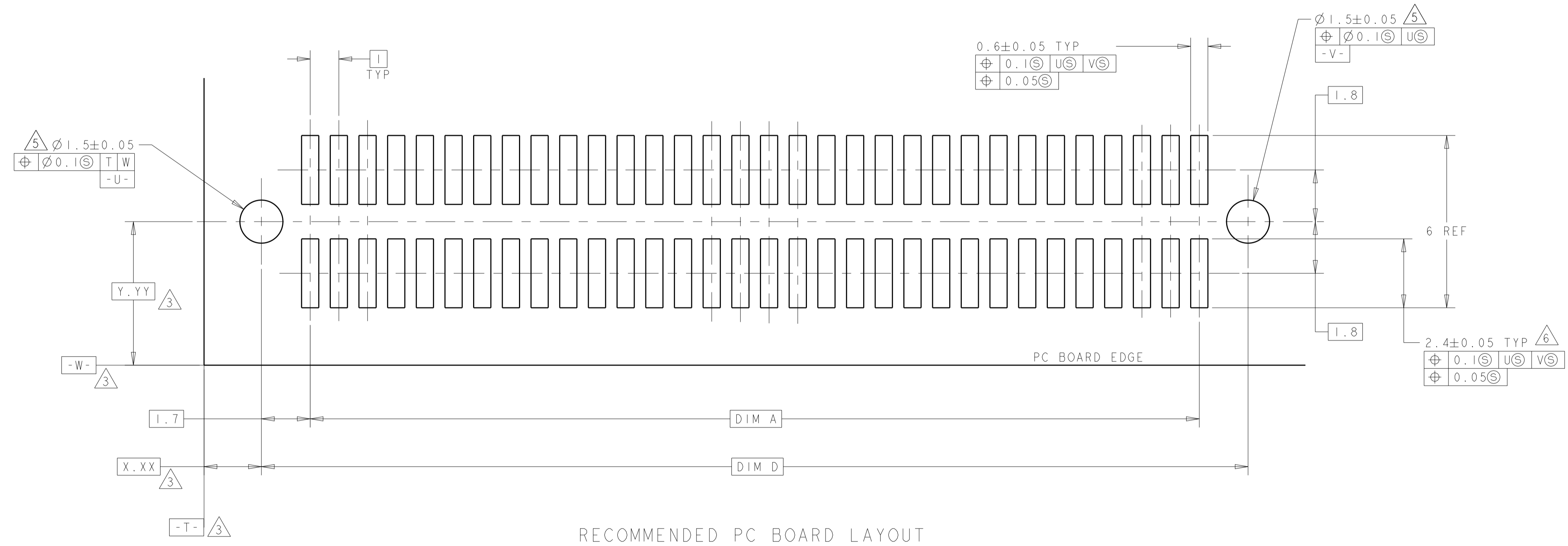
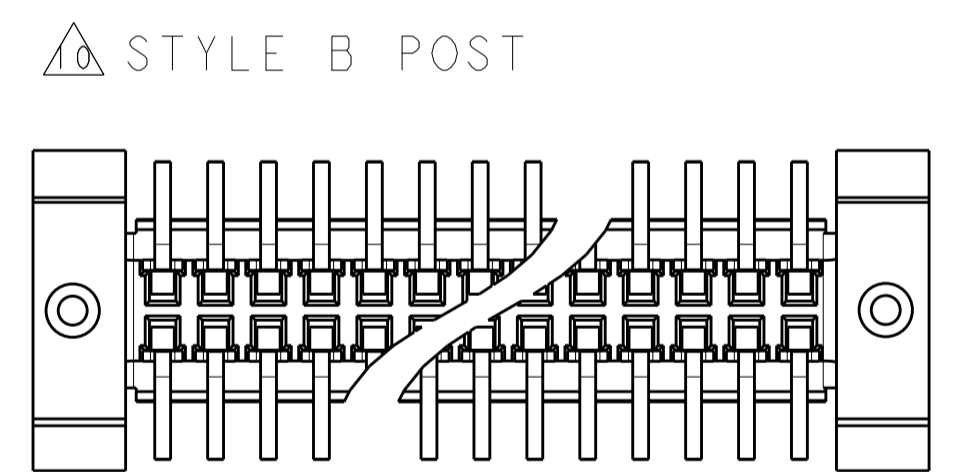
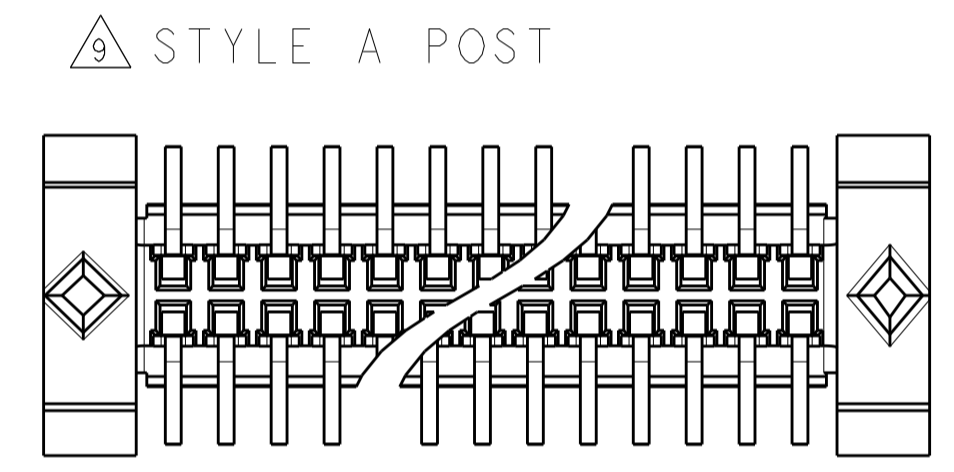
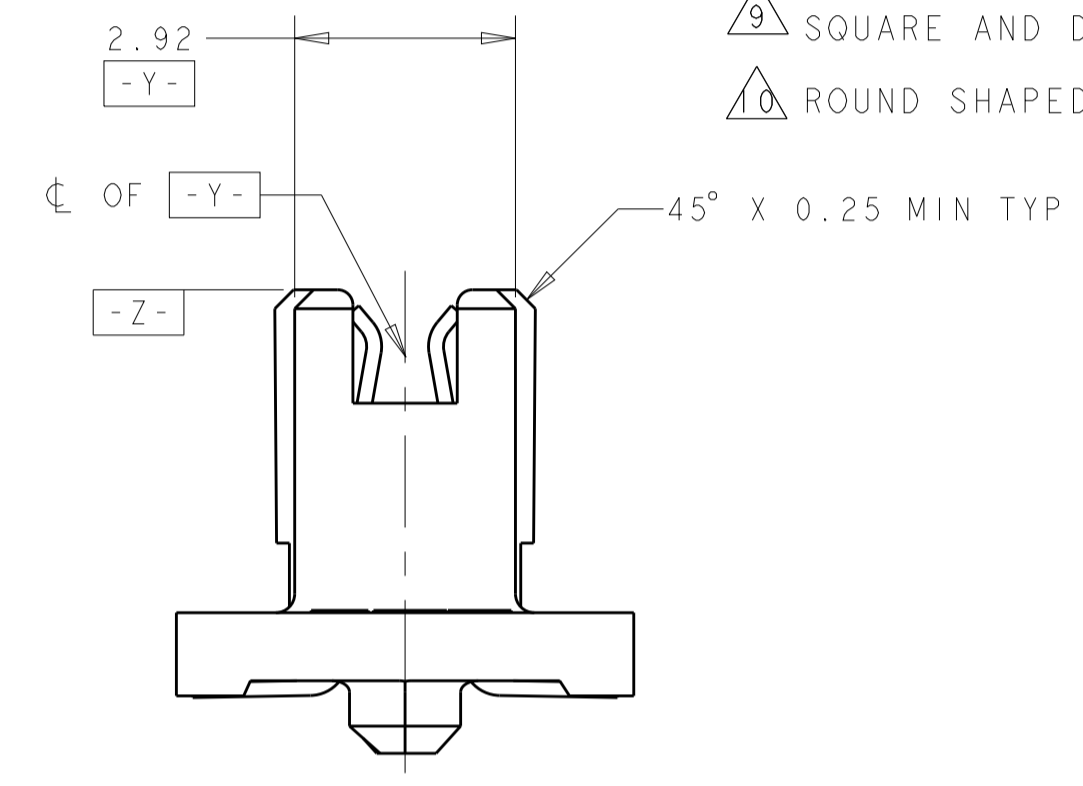
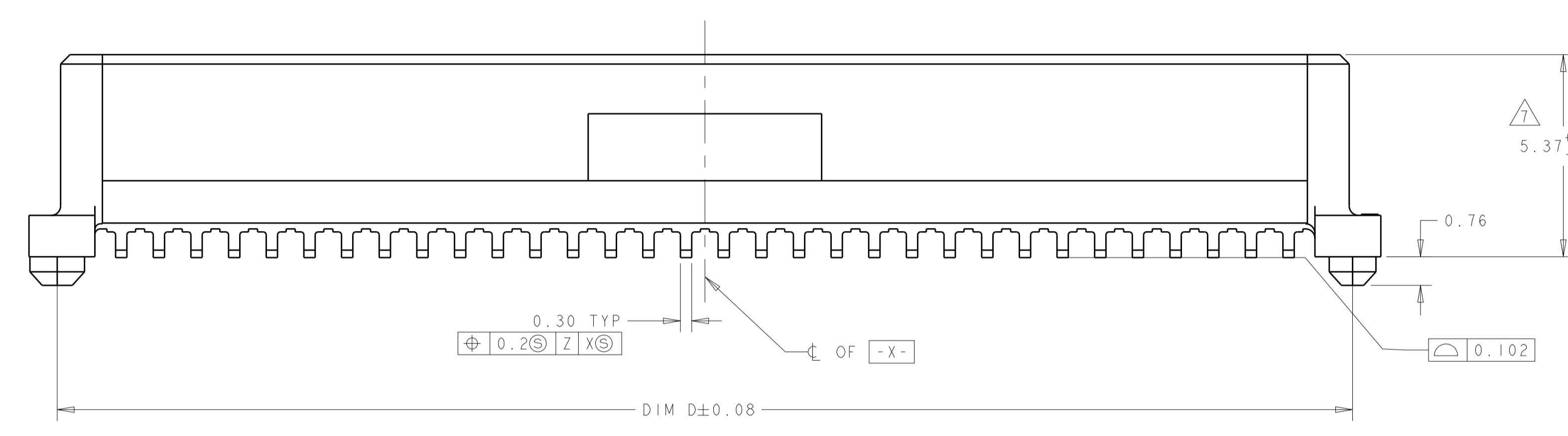
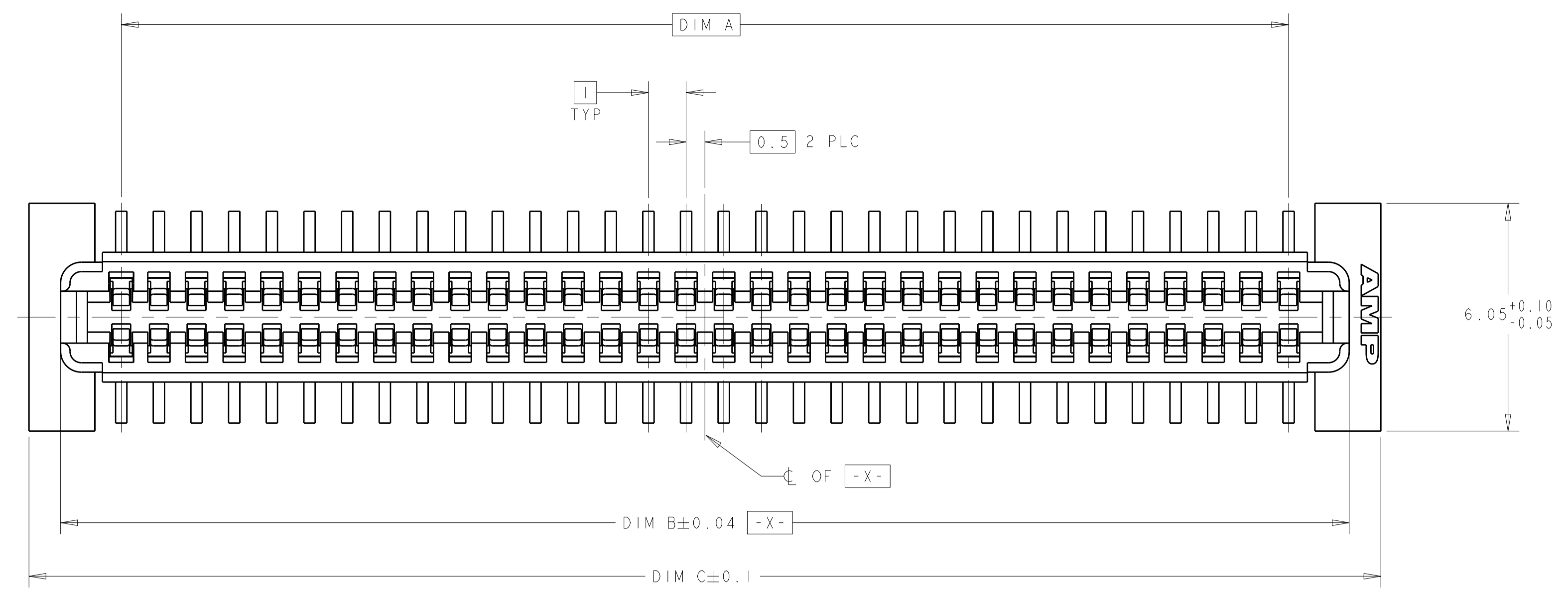


LOC	DIST	REVISIONS			
P	LTN	DESCRIPTION	DATE	DMN	APVD
K		REVISED PER ECR-14-016951	11FEB2015	J.T	W.H



RECOMMENDED PC BOARD LAYOUT

1. HOUSING MATERIAL: HIGH TEMPERATURE THERMOPLASTIC, COLOR; BLACK. CONTACT MATERIAL: PHOSPHOR BRONZE.
2. CONTACT FINISH: NICKEL UNDERPLATE ALL OVER, MATING SURFACES PLATED TO MEET PLI PERFORMANCE REQUIREMENTS OF INDUSTRY SPECIFICATION EIA-700AAAB, SOLDER TAILS PLATED TIN-LEAD.
3. DATUM LOCATIONS AND BASIC DIMENSIONS TO BE ESTABLISHED BY THE CUSTOMER. CONSULT AMP ENGINEERING WHEN PLACING MULTIPLE CONNECTORS ON A PC BOARD.
4. PACKAGED IN TAPE ON REEL PER EIA-481.
5. 1.5 MIN DIAMETER HOLE SHOULD BE USED IF USING POST STYLE "A" AND PLACING ON PCB WITH VACUUM PLACEMENT EQUIPMENT.
6. SHORTER SOLDER LANDS MAY BE USED PER EIA 700AAAB, HOWEVER 2.4 LENGTH ASSURES OPTIMUM SOLDER FILLET REGARDLESS OF MANUFACTURER OF CONNECTOR.
7. REFERRED TO AS DIM H = 5.30±0.1 IN EIA700AAAB SPECIFICATION.
8. CONTACT FINISH: 0.002 MINIMUM BRIGHT TIN-LEAD (93-7) ON SOLDER AREA, 0.00127 MINIMUM GOLD ON MATING AREA, BOTH OVER 0.00127 MINIMUM NICKEL ON ENTIRE CONTACT.
9. SQUARE AND DIAMOND SHAPED POSTS
10. ROUND SHAPED POSTS

POST STYLE	FINISH	DIM D	DIM C	DIM B	DIM A	STACK HGTS	POS	PART NO
10	8	44.4	45.9	44.22	41	8.9, 10	84	3-120521-2
10	8	34.4	35.9	34.22	31	8.9, 10	64	3-120521-1
10	2	44.4	45.9	44.22	41	8.9, 10	84	2-120521-2
10	2	34.4	35.9	34.22	31	8.9, 10	64	2-120521-1
9	8	44.4	45.9	44.22	41	8.9, 10	84	1-120521-2
9	8	34.4	35.9	34.22	31	8.9, 10	64	1-120521-1
9	2	44.4	45.9	44.22	41	8.9, 10	84	120521-2
9	2	34.4	35.9	34.22	31	8.9, 10	64	120521-1

THIS DRAWING IS A CONTROLLED DOCUMENT. DMN J. REED 27/11/97

TE Connectivity

RECEPTACLE ASSY, 1.0mm FH (IEEE1386) CONNECTOR

SIZE: 100779 C=120521

SCALE: 10:1 SHEET 1 OF 1 REV K